



Part Number : [15477508](#)
Product Description : 2.54mm Pitch C-Grid Header, Through Hole, Dual Row, Vertical, High Temperature, Shrouded, with Peg, 8 Circuits, Tin (Sn) Plating
Series Number : 70568
Status : Active
Product Category : PCB Headers and Receptacles
Engineering Number : A-70568-0002



Documents & Resources

Drawings
[015477508_sd.pdf](#)
[PK-70873-0018-001.pdf](#)

3D Models and Design Files
[015477508_stp.zip](#)

Specifications
[PS-70567-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)6225-DC (07 Nov 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements
- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	PCB Headers and Receptacles
Series	70568
Description	2.54mm Pitch C-Grid Header, Through Hole, Dual Row, Vertical, High Temperature, Shrouded, with Peg, 8 Circuits, Tin (Sn) Plating
Application	Signal, Wire-to-Board
Component Type	PCB Header
Product Name	C-Grid
UPC	800754627023

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	2.5A
Voltage - Maximum	250V

Physical

Breakaway	No
Circuits (Loaded)	8
Circuits (maximum)	8
Color - Resin	Black
First Mate / Last Break	No
Flammability	94V-0

Glow-Wire Capable	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	2.114/g
Number of Rows	2
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	3.30mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.40mm
Pitch - Mating Interface	2.54mm
Pitch - Termination Interface	2.54mm
Plating min - Mating	3.810µm
Plating min - Termination	3.810µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Shrouded	Fully
Stackable	No
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	1
Max-Temp	245

Mates With / Use With

Mates with Part(s)

Description	Part Number
C-Grid Vertical, Dual Row, High Profile, Through Hole PCB Receptacles	<u>71850</u>

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